

Wiring, Printed Certified for Canada - Component

COMPANY
RELIANCE TECHNOLOGY DEVELOPMENT LTD
Unit H, 14th Floor
Mai Luen Industrial Building
23-31 Kung Yip Street
Kwai Chung, N T, Hong Kong

E322179

Cond Width				Max Report				Max							
Type	Min		Cond	SS/	Area	date	Surface	Assembly		Solder		Solder	Oper	Meets	C
	Min	Edge	Thk	DS/	Diam	After	Mount	Process	Process	Limits	Temp	Flame	UL796	T	
	mm	mm	mic	DSO	mm	2022-01-01	Technology	Temp	Cycles	°C	sec	°C	Class	DSR	I
Multilayer printed wiring boards															
RT-2 (ASP 1)	0.075	0.10	12 Int:102	DS	50.8	Yes	Yes	260	3	-	-	130	V-0	All	*
RT-4	0.076	0.076	17 Int:68	DS	50.8	No	-	-	-	260	10	130	V-0	All	*
Single layer metal base printed wiring boards															
RT-M2 (ASP 1)	0.13	0.39	17	SS	50.8	Yes	Yes	260	1	288	10	130	V-0	All	0
Single layer printed wiring boards															
RT-1 (ASP 1)	0.075	0.10	15	DS	50.8	Yes	Yes	260	3	-	-	130	V-0	All	*
RT-3	0.1	0.11	17	DS	50.8	No	-	-	-	260	10	130	V-0	All	*

* - CTI marking is optional and may be marked on the printed wiring board.
(ASP 1) - Assembly solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation.

Marking: Company name or trademark  or file number and type designation and the Recognized Component Mark for Canada, . May be followed by a suffix to denote factory identification or flammability classification..

Last Updated on 2023-07-17

并不是所有出现在本数据库中的公司名称和产品都满足了UL 跟踪检验服务的要求。只有带有 UL 标志的产品，才应该被视为经过 UL 认证，并满足UL 跟踪检验服务的要求。注意查看产品上的标志。

UL 允许在线认证目录中所含材料的复制遵循以下条件：1.指南信息、装配、构造、设计、系统和/或认证（文件）必须在不篡改任何数据（或图纸）的情况下完整且无误导性地呈现。2.“经 UL 允许从在线认证目录转载”声明必须出现在所摘取材料的邻近位置。此外，转载材料必须包含以下格式的版权声明： "©2023 UL LLC."